DATASHEET

Vertical Foup for Wafer 12” (300mm)

Reliable wafer shipping solution ensuring protection from contamination and mechanical damage

Engineered for wafers mounted on flex, dicing, or film frames, this vertical shipper secures frame-supported wafers in a standing orientation. Its precision-molded slots immobilize frames, and its inner contours cradle the metal or plastic frame rather than the wafer surface, preventing wafer slippage and micro-crack damage during handling.

A spring design in the upper cover effectively prevents frame movement and wafer breakage. Made from ESD-protective polymer materials, which resist ionic contamination, outgassing, and static discharge.

Dust-free cleaning and packaging after production, suitable for 100-class purification workshops, ensures particle-free storage, which is critical in maintaining the integrity of sensitive wafers throughout the shipping process.

Flex Frame Wafer Shippers are the ideal solution for semiconductor manufacturers seeking reliable and efficient transportation of multiple wafers mounted on dicing, flex, or film frames.

Features & Benefits

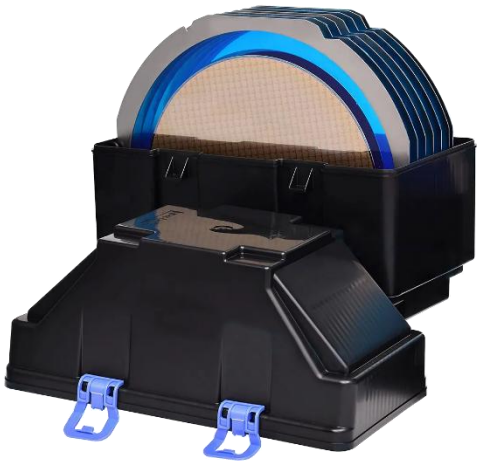
Wafer’s size: 300mm (12”)

Made from low particle/ionic/outgassing material

Vertically secures wafers already mounted on flex, dicking, or film frames

Spring design in the upper cover effectively prevents frame movement and wafer breakage

Reusable for cost-efficient shipping



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Technical Data

Dimensions (L×W×H)	397,5 × 228 × 415,5mm
Load Capacity	13 pieces maximum
Material	Conductive PP
Couleur	Black

Property	Test method	Rated values
Density	ISO 1183-1 (23°C)	1,0 g/cm³
Melt Index (350°C/5kg)	ASTM D-1238	15,0g/10min
Shrinkage Percentage	ISO 2577	1,2 à 1,6%
Tensile Strength	ISO 527-2 (50mm/min)	25 MPa
Tensile Strain at Break	ISO 527-2 (50mm/min)	10%
Flexural Strength (fracture)	ISO 178 (2mm/min)	27MPa
Flexural Modulus	ISO 178 (2mm/min)	1150MPa
LZOD Notch Impact Strength (3,2mm)	ISO 180 (23°C)	30 kJ/m²
Surface Resistivity	ASTM D-257	1,0 × 10⁴ à 1,0 × 10⁹Ω/sq
Flame retardant Rating	UL 94	Classe HB

** The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.*

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